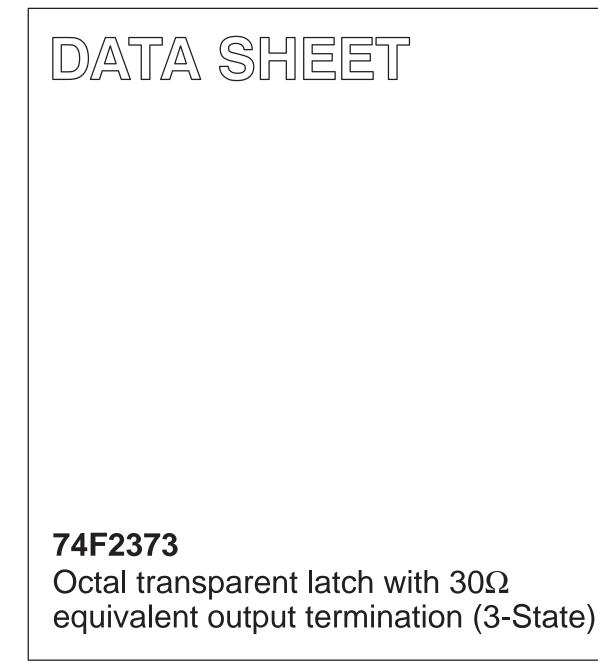
INTEGRATED CIRCUITS



Product specification Supersedes data of 1995 Jun 20 IC15 Data Handbook

1999 Feb 01



Philips Semiconductors

74F2373

FEATURES

- 8-bit transparent latch
- 30 Ohm output termination for driving DRAM
- 3-State outputs glitch free during power-up and power-down
- Common 3-State output register
- Independent register and 3-State buffer operation

DESCRIPTION

The 74F2373 is an octal transparent latch coupled to eight 3-State output devices. The two sections of the device are controlled independently by enable (E) and output enable (\overline{OE}) control gates.

The 30 Ohm series termination on the outputs reduces over/undershoot, making them ideal for driving DRAM

The data on the D inputs is transferred to the latch outputs when the enable (E) input is high. The latch remains transparent to the data input while E is high, and stores the data that is present one setup time before the high-to-low enable transition.

The 3-State output buffers are designed to drive heavily loaded 3-State buses, MOS memories, or MOS microprocessors.

The active low output enable (\overline{OE}) controls all eight 3-State buffers independent of the latch operation. When \overline{OE} is low, latched or transparent data appears at the output.

When \overline{OE} is high, the outputs are in high impedance "off" state, which means they will neither drive nor load the bus.

ТҮРЕ	DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F2373	4.5ns	35mA

ORDERING INFORMATION

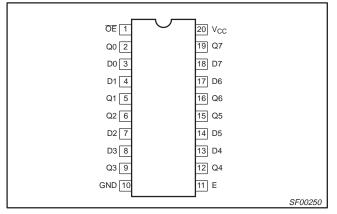
	ORDER CODE	
DESCRIPTION	COMMERCIAL RANGE V_{CC} = 5V ±10%, T _{amb} = 0°C to +70°C	DRAWING NUMBER
20-pin plastic DIP	N74F2373N	SOT146-1
20-pin plastic SOL	N74F2373D	SOT163-1

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

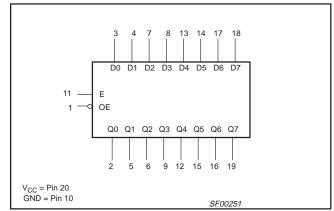
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0 - D7	Data inputs	1.0/1.0	20µA/0.6mA
E	Enable input (active high)	1.0/1.0	20µA/0.6mA
ŌE	Output enable inputs (active low)	1.0/1.0	20µA/0.6mA
Q0 - Q7	3-State outputs	150/40	3.0mA/3.0mA

NOTE: One (1.0) FAST unit load is defined as: 20µA in the high state and 0.6mA in the low state.

PIN CONFIGURATION

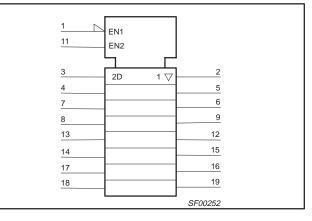


LOGIC SYMBOL

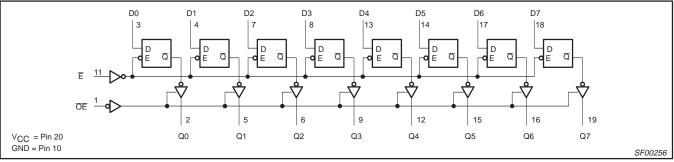


74F2373

IEC/IEEE SYMBOL



LOGIC DIAGRAM



FUNCTION TABLE

	INPUTS		INTERNAL	OUTPUTS	OPERATING MODE
OE	E	Dn	REGISTER	Q0 - Q7	OPERATING MODE
L	Н	L	L	L	Enable and read register
L	Н	Н	Н	н	Enable and read register
L	\downarrow	I	L	L	Lateband read register
L	\downarrow	h	Н	Н	Latch and read register
L	L	Х	NC	NC	Hold
Н	L	Х	NC	Z	Dischle outputs
Н	Н	Dn	Dn	Z	Disable outputs

NOTES:

H = High-voltage level

h = High state must be present one setup time before the high-to-low enable transition

Low-voltage level L =

L = Low state must be present one setup time before the high-to-low enable transition

NC= No change

Don't care

 $\begin{array}{c} X = \\ Z = \\ \downarrow = \end{array}$ High impedance "off" state

High-to-low enable transition

74F2373

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in high output state	-0.5 to V _{CC}	V
I _{OUT}	Current applied to output in low output state	24	mA
T _{amb}	Operating free air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		LIMITS		UNIT
STWIDUL		MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V
V _{IL}	Low-level input voltage			0.8	V
I _{lk}	Input clamp current			-18	mA
I _{OH}	High-level output current			-3*	mA
I _{OL}	Low-level output current			5*	mA
T _{amb}	Operating free air temperature range	0		+70	°C
12mA wit	h reduced noise margin	•			-

12mA with reduced noise margin

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST			LIMITS		UNIT
STNIDUL	FARAMETER	CONDITIONS	CONDITIONS ¹				
		$V_{CC} = MIN, V_{IL} = MAX,$	±10%V _{CC}	2.4			V
		V _{IH} = MIN, I _{OH} = -3mA	$\pm 5\% V_{CC}$	2.7	3.4		V
V _{OH}	High-level output voltage	$V_{CC} = MIN, V_{IL} = MAX,$	±10%V _{CC}	2.0			V
		$V_{IH} = MIN, I_{OH} = -12mA$	$\pm 5\% V_{CC}$	2.0			V
		$V_{CC} = MIN, V_{IL} = MAX,$	±10%V _{CC}		0.42	0.50	V
V-	Low-level output voltage	$V_{IH} = MIN, I_{OL} = -5mA$	±5%V _{CC}		0.42	0.50	V
V _{OL}		$V_{CC} = MIN, V_{IL} = MAX,$	±10%V _{CC}		0.67		V
		$V_{IH} = MIN, I_{OL} = 12mA$	±5%V _{CC}		0.67		V
V _{IK}	Input clamp voltage	$V_{CC} = MIN, I_I = I_{IK}$			-0.73	-1.2	V
կ	Input current at maximum input voltage	$V_{CC} = MAX, V_I = 7.0V$				100	μΑ
I _{IH}	High-level input current	$V_{CC} = MAX, V_I = 2.7V$				20	μA
Ι _{ΙL}	Low-level input current	$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
I _{OZH}	Off-state output current, high-level voltage applied	$V_{CC} = MAX, V_O = 2.7V$				50	μΑ
I _{OZL}	Off-state output current, low-level voltage applied	$V_{CC} = MAX, V_O = 0.5V$				-50	μΑ
I _{OS}	Short-circuit output current ³	V _{CC} = MAX		-60		-150	mA
I _{CC}	Supply current (total)	V _{CC} = MAX			35	60	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

2. All typical values are at $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$.

3. Not more than one output should be shorted at a time. For testing IOS, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

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AC ELECTRICAL CHARACTERISTICS

					LIN	NITS		
SYMBOL	PARAMETER	TEST CONDITION	v.	_{mb} = +25 _{CC} = +5.0 DpF, R _L :	V	T _{amb} = 0°C V _{CC} = +5. C _L = 50pF,		UNIT
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay Dn to Qn	Waveform 2	3.0 2.0	5.3 3.7	8.0 6.0	3.0 2.0	9.0 7.0	ns
t _{PLH} t _{PHL}	Propagation delay E to Qn	Waveform 1	5.0 3.0	9.0 4.0	12.0 8.0	5.0 3.0	12.5 8.5	ns
t _{PZH} t _{PZL}	Output enable time to high or low level	Waveform 4 Waveform 5	2.0 2.0	5.0 5.6	12.0 8.0	2.0 2.0	12.5 8.5	ns
t _{PHZ} t _{PLZ}	Output disable time from high or low level	Waveform 4 Waveform 5	2.0 2.0	4.5 3.8	6.5 5.5	2.0 2.0	7.5 6.5	ns

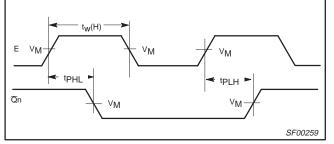
AC SETUP REQUIREMENTS

					LIN	IITS		
SYMBOL	PARAMETER	TEST CONDITION	v.	_{mb} = +25 _{CC} = +5.0 DpF, R _L :	v	T _{amb} = 0°C V _{CC} = +5. C _L = 50pF,	0V \pm 10%	UNIT
			MIN	TYP	MAX	MIN	MAX	1
t _{su} (H) t _{su} (L)	Setup time, high or low level Dn to E	Waveform 3	0 1.0			0 1.0		ns
t _h (H) t _h (L)	Hold time, high or low level Dn to E	Waveform 3	3.0 3.0			3.0 3.0		ns
t _w (H)	E Pulse width, high	Waveform 1	3.5			4.0		ns

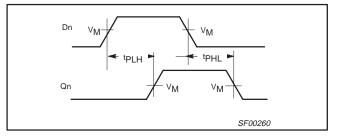
AC WAVEFORMS

For all waveforms, $V_M = 1.5V$.

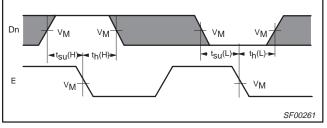
The shaded areas indicate when the input is permitted to change for predictable output performance.



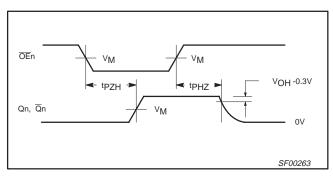
Waveform 1. Propagation delay for enable to output and enable pulse width



Waveform 2. Propagation delay for data to output



Waveform 3. Data setup time and hold times



Waveform 4. 3-State output enable time to high level and output disable time from high level

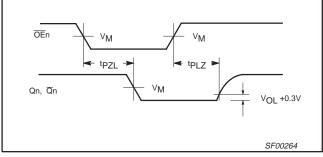
Product specification

74F2373

SF00265

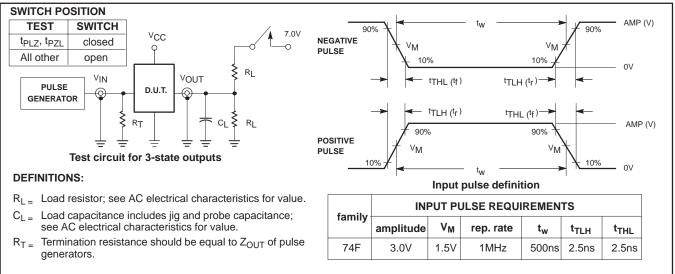
AC WAVEFORMS (Continued)

For all waveforms, V_M = 1.5V. The shaded areas indicate when the input is permitted to change for predictable output performance.



Waveform 5. 3-State output enable time to low level and output disable time from low level

TEST CIRCUIT AND WAVEFORMS



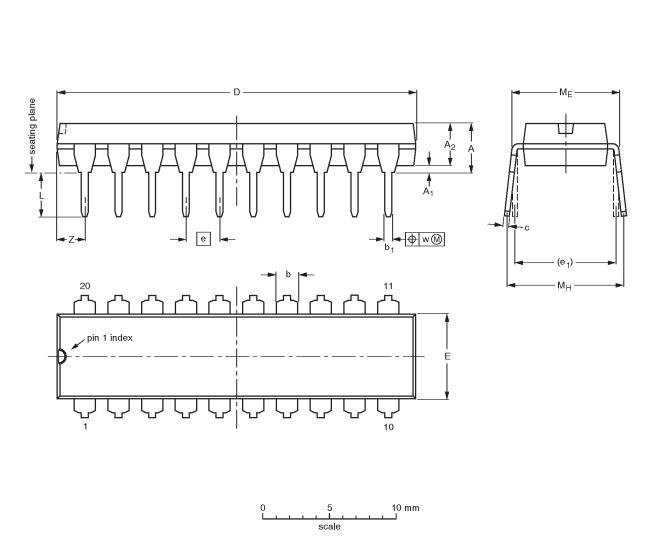
1999 Feb 01

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SOT146-1

Product specification

DIP20: plastic dual in-line package; 20 leads (300 mil)



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

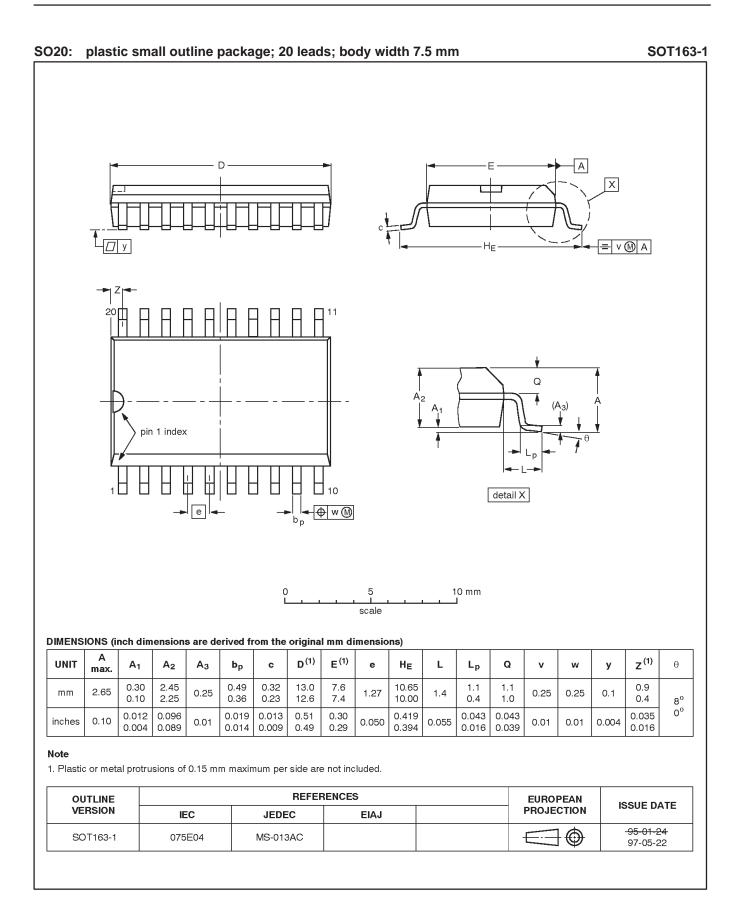
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFEF	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT146-1			SC603		-92-11-17 95-05-24

74F2373

Product specification



74F2373

NOTES

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition - Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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